Title (en)

SIC-BOUND DIAMOND HARD MATERIAL PARTICLES, POROUS COMPONENT FORMED WITH SIC-BOUND DIAMOND PARTICLES, METHOD OF PRODUCING SAME AND USE THEREOF

Title (de)

SiC-GEBUNDENE DIAMANTHARTSTOFFPARTIKEL, PORÖSES BAUTEIL, DAS MIT SiC-GEBUNDENEN DIAMANTPARTIKELN GEBILDET IST, VERFAHREN ZU DEREN HERSTELLUNG SOWIE DEREN VERWENDUNG

Title (fr)

PARTICULE DE CÉRAMIQUE DE DIAMANT RELIÉE À DU SIC, MODULE POREUX QUI EST CONSTITUÉ DE PARTICULES DE DIAMANT RELIÉES À DU SIC, LEUR PROCÉDÉ DE FABRICATION ET LEUR UTILISATION

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Abstract (en)

[origin: WO2019175333A1] The invention relates to SiC-bound diamond hard material particles, a porous component formed with SiC-bound diamond particles, methods for producing same and the use thereof. Diamond hard material particles and components have a composition of 30 vol. % to 65 vol. % diamond, 70 vol. % to 35 vol. % SiC and 0 to 30 vol. % Si, and a component has a porosity in the range of 10% to 40%.

IPC 8 full level

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CPC (source: EP KR US)

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